



Welcome to **E-XFL.COM** 

**Embedded - System On Chip (SoC):** The Heart of Modern Embedded Systems

Embedded - System On Chip (SoC) refers to an integrated circuit that consolidates all the essential components of a computer system into a single chip. This includes a microprocessor, memory, and other peripherals, all packed into one compact and efficient package. SoCs are designed to provide a complete computing solution, optimizing both space and power consumption, making them ideal for a wide range of embedded applications.

What are **Embedded - System On Chip (SoC)?** 

**System On Chip (SoC)** integrates multiple functions of a computer or electronic system onto a single chip. Unlike traditional multi-chip solutions. SoCs combine a central

Details	
Product Status	Discontinued at Digi-Key
Architecture	MCU, FPGA
Core Processor	Dual ARM® Cortex®-A9 MPCore™ with CoreSight™
Flash Size	-
RAM Size	256KB
Peripherals	DMA, POR, WDT
Connectivity	EBI/EMI, Ethernet, I <sup>2</sup> C, MMC/SD/SDIO, SPI, UART/USART, USB OTG
Speed	1.5GHz
Primary Attributes	FPGA - 160K Logic Elements
Operating Temperature	0°C ~ 100°C (TJ)
Package / Case	672-BBGA, FCBGA
Supplier Device Package	672-FBGA, FC (27x27)
Purchase URL	https://www.e-xfl.com/product-detail/intel/10as016e3f27e1sg

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong



# Intel® Arria® 10 Device Overview

The Intel® Arria® 10 device family consists of high-performance and power-efficient 20 nm mid-range FPGAs and SoCs.

Intel Arria 10 device family delivers:

- Higher performance than the previous generation of mid-range and high-end FPGAs.
- Power efficiency attained through a comprehensive set of power-saving technologies.

The Intel Arria 10 devices are ideal for high performance, power-sensitive, midrange applications in diverse markets.

Table 1. Sample Markets and Ideal Applications for Intel Arria 10 Devices

Market	Applications
Wireless	Channel and switch cards in remote radio heads     Mobile backhaul
Wireline	<ul> <li>40G/100G muxponders and transponders</li> <li>100G line cards</li> <li>Bridging</li> <li>Aggregation</li> </ul>
Broadcast	<ul> <li>Studio switches</li> <li>Servers and transport</li> <li>Videoconferencing</li> <li>Professional audio and video</li> </ul>
Computing and Storage	Flash cache     Cloud computing servers     Server acceleration
Medical	Diagnostic scanners     Diagnostic imaging
Military	Missile guidance and control     Radar     Electronic warfare     Secure communications

## **Related Information**

Intel Arria 10 Device Handbook: Known Issues

Lists the planned updates to the *Intel Arria 10 Device Handbook* chapters.

Intel Corporation. All rights reserved. Intel, the Intel logo, Altera, Arria, Cyclone, Enpirion, MAX, Nios, Quartus and Stratix words and logos are trademarks of Intel Corporation or its subsidiaries in the U.S. and/or other countries. Intel warrants performance of its FPGA and semiconductor products to current specifications in accordance with Intel's standard warranty, but reserves the right to make changes to any products and services at any time without notice. Intel assumes no responsibility or liability arising out of the application or use of any information, product, or service described herein except as expressly agreed to in writing by Intel. Intel customers are advised to obtain the latest version of device specifications before relying on any published information and before placing orders for products or services.

ISO 9001:2008 Registered



# **Key Advantages of Intel Arria 10 Devices**

Table 2. Key Advantages of the Intel Arria 10 Device Family

Advantage	Supporting Feature
Enhanced core architecture	Built on TSMC's 20 nm process technology     60% higher performance than the previous generation of mid-range FPGAs     15% higher performance than the fastest previous-generation FPGA
High-bandwidth integrated transceivers	<ul> <li>Short-reach rates up to 25.8 Gigabits per second (Gbps)</li> <li>Backplane capability up to 12.5 Gbps</li> <li>Integrated 10GBASE-KR and 40GBASE-KR4 Forward Error Correction (FEC)</li> </ul>
Improved logic integration and hard IP blocks	8-input adaptive logic module (ALM)     Up to 65.6 megabits (Mb) of embedded memory     Variable-precision digital signal processing (DSP) blocks     Fractional synthesis phase-locked loops (PLLs)     Hard PCI Express Gen3 IP blocks     Hard memory controllers and PHY up to 2,400 Megabits per second (Mbps)
Second generation hard processor system (HPS) with integrated ARM* Cortex*-A9* MPCore* processor	Tight integration of a dual-core ARM Cortex-A9 MPCore processor, hard IP, and an FPGA in a single Intel Arria 10 system-on-a-chip (SoC)  Supports over 128 Gbps peak bandwidth with integrated data coherency between the processor and the FPGA fabric
Advanced power savings	Comprehensive set of advanced power saving features Power-optimized MultiTrack routing and core architecture Up to 40% lower power compared to previous generation of mid-range FPGAs Up to 60% lower power compared to previous generation of high-end FPGAs

# **Summary of Intel Arria 10 Features**

**Table 3.** Summary of Features for Intel Arria 10 Devices

Feature	Description
Technology	<ul> <li>TSMC's 20-nm SoC process technology</li> <li>Allows operation at a lower V<sub>CC</sub> level of 0.82 V instead of the 0.9 V standard V<sub>CC</sub> core voltage</li> </ul>
Packaging	<ul> <li>1.0 mm ball-pitch Fineline BGA packaging</li> <li>0.8 mm ball-pitch Ultra Fineline BGA packaging</li> <li>Multiple devices with identical package footprints for seamless migration between different FPGA densities</li> <li>Devices with compatible package footprints allow migration to next generation high-end Stratix® 10 devices</li> <li>RoHS, leaded<sup>(1)</sup>, and lead-free (Pb-free) options</li> </ul>
High-performance FPGA fabric	<ul> <li>Enhanced 8-input ALM with four registers</li> <li>Improved multi-track routing architecture to reduce congestion and improve compilation time</li> <li>Hierarchical core clocking architecture</li> <li>Fine-grained partial reconfiguration</li> </ul>
Internal memory blocks	M20K—20-Kb memory blocks with hard error correction code (ECC)     Memory logic array block (MLAB)—640-bit memory
	continued

<sup>(1)</sup> Contact Intel for availability.

## A10-OVERVIEW | 2018.04.09



Feature		Description
Embedded Hard IP blocks	Variable-precision DSP	<ul> <li>Native support for signal processing precision levels from 18 x 19 to 54 x 54</li> <li>Native support for 27 x 27 multiplier mode</li> <li>64-bit accumulator and cascade for systolic finite impulse responses (FIRs)</li> <li>Internal coefficient memory banks</li> <li>Preadder/subtractor for improved efficiency</li> <li>Additional pipeline register to increase performance and reduce power</li> <li>Supports floating point arithmetic:         <ul> <li>Perform multiplication, addition, subtraction, multiply-add, multiply-subtract, and complex multiplication.</li> <li>Supports multiplication with accumulation capability, cascade summation, and cascade subtraction capability.</li> <li>Dynamic accumulator reset control.</li> <li>Support direct vector dot and complex multiplication chaining multiply floating point DSP blocks.</li> </ul> </li> </ul>
	Memory controller	DDR4, DDR3, and DDR3L
	PCI Express*	PCI Express (PCIe*) Gen3 (x1, x2, x4, or x8), Gen2 (x1, x2, x4, or x8) and Gen1 (x1, x2, x4, or x8) hard IP with complete protocol stack, endpoint, and root port
	Transceiver I/O	10GBASE-KR/40GBASE-KR4 Forward Error Correction (FEC)     PCS hard IPs that support:
Core clock networks	<ul> <li>667 MHz externa</li> <li>800 MHz LVDS in</li> <li>Global, regional, and</li> </ul>	c clocking, depending on the application: I memory interface clocking with 2,400 Mbps DDR4 interface terface clocking with 1,600 Mbps LVDS interface I peripheral clock networks are not used can be gated to reduce dynamic power
Phase-locked loops (PLLs)	<ul> <li>Support integer r</li> <li>Fractional mode s</li> <li>Integer PLLs:</li> <li>Adjacent to gene</li> </ul>	rnthesis, clock delay compensation, and zero delay buffering (ZDB) mode and fractional mode support with third-order delta-sigma modulation
FPGA General-purpose I/Os (GPIOs)	On-chip termination	ry pair can be configured as receiver or transmitter (OCT) -ended LVTTL/LVCMOS interfacing
External Memory Interface	<ul><li>DDR4—speeds up</li><li>DDR3—speeds up</li></ul>	oller— DDR4, DDR3, and DDR3L support to 1,200 MHz/2,400 Mbps to 1,067 MHz/2,133 Mbps to 1,067 MHz/2,133 Mbps to 1,067 MHz/2,134 Mhz/2,134 Mbps to 1,067 Mhz/2,134



Feature	Description
	<ul> <li>Dynamic reconfiguration of the transceivers and PLLs</li> <li>Fine-grained partial reconfiguration of the core fabric</li> <li>Active Serial x4 Interface</li> </ul>
Power management	SmartVID     Low static power device options     Programmable Power Technology     Intel Quartus Prime integrated power analysis
Software and tools	<ul> <li>Intel Quartus Prime design suite</li> <li>Transceiver toolkit</li> <li>Platform Designer system integration tool</li> <li>DSP Builder for Intel FPGAs</li> <li>OpenCL™ support</li> <li>Intel SoC FPGA Embedded Design Suite (EDS)</li> </ul>

#### **Related Information**

Intel Arria 10 Transceiver PHY Overview

Provides details on Intel Arria 10 transceivers.

## **Intel Arria 10 Device Variants and Packages**

#### Table 4. **Device Variants for the Intel Arria 10 Device Family**

Variant	Description
Intel Arria 10 GX	FPGA featuring 17.4 Gbps transceivers for short reach applications with 12.5 backplane driving capability.
Intel Arria 10 GT	<ul> <li>FPGA featuring:</li> <li>17.4 Gbps transceivers for short reach applications with 12.5 backplane driving capability.</li> <li>25.8 Gbps transceivers for supporting CAUI-4 and CEI-25G applications with CFP2 and CFP4 modules.</li> </ul>
Intel Arria 10 SX	SoC integrating ARM-based HPS and FPGA featuring 17.4 Gbps transceivers for short reach applications with 12.5 backplane driving capability.

## **Intel Arria 10 GX**

This section provides the available options, maximum resource counts, and package plan for the Intel Arria 10 GX devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the Intel FPGA Product Selector.

## **Related Information**

Intel FPGA Product Selector

Provides the latest information on Intel products.



## **Maximum Resources**

Table 5. Maximum Resource Counts for Intel Arria 10 GX Devices (GX 160, GX 220, GX 270, GX 320, and GX 480)

Resc	ource		Product Line								
		GX 160	GX 220	GX 270	GX 320	GX 480					
Logic Elements	(LE) (K)	160	220	270	320	480					
ALM		61,510	80,330	101,620	119,900	183,590					
Register		246,040	321,320	406,480	479,600	734,360					
Memory (Kb)	M20K	8,800	11,740	15,000	17,820	28,620					
	MLAB	1,050	1,690	2,452	2,727	4,164					
Variable-precision DSP Block		156	192	192 830 985		1,368					
18 x 19 Multipli	er	312	384	1,660	1,970	2,736					
PLL	Fractional Synthesis	6	6	8	8	12					
	I/O	6	6	8	8	12					
17.4 Gbps Trans	sceiver	12	12	12 24 24		36					
GPIO (3)		288	288 384		384	492					
LVDS Pair (4)		120 120		168	168	222					
PCIe Hard IP Block		1	1	2	2	2					
Hard Memory C	ontroller	6	6 6 8		8	12					

 $<sup>^{(3)}</sup>$  The number of GPIOs does not include transceiver I/Os. In the Intel Quartus Prime software, the number of user I/Os includes transceiver I/Os.

<sup>(4)</sup> Each LVDS I/O pair can be used as differential input or output.



## **Available Options**

Figure 2. Sample Ordering Code and Available Options for Intel Arria 10 GT Devices





#### **Maximum Resources**

Table 10. Maximum Resource Counts for Intel Arria 10 GT Devices

Reso	ource	Product Line				
		GT 900	GT 1150			
Logic Elements (LE) (K)		900	1,150			
ALM		339,620	427,200			
Register		1,358,480	1,708,800			
Memory (Kb)	M20K	48,460	54,260			
	MLAB	9,386	12,984			
Variable-precision DSP Block		1,518	1,518			
18 x 19 Multiplier		3,036	3,036			
PLL	Fractional Synthesis	32	32			
	I/O	16	16			
Transceiver	17.4 Gbps	72 <sup>(5)</sup>	72 <sup>(5)</sup>			
	25.8 Gbps	6	6			
GPIO <sup>(6)</sup>		624	624			
LVDS Pair <sup>(7)</sup>		312	312			
PCIe Hard IP Block		4	4			
Hard Memory Controller		16	16			

#### **Related Information**

Intel Arria 10 GT Channel Usage

Configuring GT/GX channels in Intel Arria 10 GT devices.

## **Package Plan**

## Table 11. Package Plan for Intel Arria 10 GT Devices

Refer to I/O and High Speed I/O in Intel Arria 10 Devices chapter for the number of 3 V I/O, LVDS I/O, and LVDS channels in each device package.

Product Line	SF45 (45 mm × 45 mm, 1932-pin FBGA)					
	3 V I/O	LVDS I/O	XCVR			
GT 900	_	624	72			
GT 1150	_	624	72			

<sup>(5)</sup> If all 6 GT channels are in use, 12 of the GX channels are not usable.

<sup>(6)</sup> The number of GPIOs does not include transceiver I/Os. In the Intel Quartus Prime software, the number of user I/Os includes transceiver I/Os.

<sup>(7)</sup> Each LVDS I/O pair can be used as differential input or output.



#### **Maximum Resources**

Table 12. Maximum Resource Counts for Intel Arria 10 SX Devices

Resource		Product Line								
		SX 160	SX 220	SX 270	SX 320	SX 480	SX 570	SX 660		
Logic Elements	s (LE) (K)	160	220	270	320	480	570	660		
ALM		61,510	80,330	101,620	119,900	183,590	217,080	251,680		
Register		246,040	321,320	406,480	479,600	734,360	868,320	1,006,720		
Memory (Kb)	M20K	8,800	11,740	15,000	17,820	28,620	36,000	42,620		
	MLAB	1,050	1,690	2,452	2,727	4,164	5,096	5,788		
Variable-precision DSP Block		156	192	830	985	1,368	1,523	1,687		
18 x 19 Multip	lier	312	384	1,660	1,970	2,736	3,046	3,374		
PLL	Fractional Synthesis	6	6	8	8	12	16	16		
	I/O	6	6	8	8	12	16	16		
17.4 Gbps Tra	nsceiver	12	12	24	24	36	48	48		
GPIO (8)		288	288	384	384	492	696	696		
LVDS Pair (9)		120	120	168	168	174	324	324		
PCIe Hard IP E	Block	1	1	2	2	2	2	2		
Hard Memory Controller		6	6	8	8	12	16	16		
ARM Cortex-As	9 MPCore	Yes	Yes	Yes	Yes	Yes	Yes	Yes		

## **Package Plan**

Table 13. Package Plan for Intel Arria 10 SX Devices (U19, F27, F29, and F34)

Refer to I/O and High Speed I/O in Intel Arria 10 Devices chapter for the number of 3 V I/O, LVDS I/O, and LVDS channels in each device package.

Product Line	U19 (19 mm × 19 mm, 484-pin UBGA)		ım × 19 mm, (27 mm × 27 mm,		F29 (29 mm × 29 mm, 780-pin FBGA)			F34 (35 mm × 35 mm, 1152-pin FBGA)				
	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR
SX 160	48	144	6	48	192	12	48	240	12	_	_	_
SX 220	48	144	6	48	192	12	48	240	12	_	_	_
SX 270	_	_	_	48	192	12	48	312	12	48	336	24
SX 320	_	_	_	48	192	12	48	312	12	48	336	24
	continued											

 $<sup>^{(8)}</sup>$  The number of GPIOs does not include transceiver I/Os. In the Intel Quartus Prime software, the number of user I/Os includes transceiver I/Os.

<sup>(9)</sup> Each LVDS I/O pair can be used as differential input or output.



Product Line		U19 nm × 19 I-pin UB			F27 (27 mm × 27 mm, 672-pin FBGA)		F29 (29 mm × 29 mm, 780-pin FBGA)			F34 (35 mm × 35 mm, 1152-pin FBGA)		
	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR
SX 480	_	_	_	_	_	_	48	312	12	48	444	24
SX 570	_	_	_	_	_	_	_	_	_	48	444	24
SX 660	_	_	_	_	_	_	_	_	_	48	444	24

## Table 14. Package Plan for Intel Arria 10 SX Devices (F35, KF40, and NF40)

Refer to I/O and High Speed I/O in Intel Arria 10 Devices chapter for the number of 3 V I/O, LVDS I/O, and LVDS channels in each device package.

<b>Product Line</b>	F35 (35 mm × 35 mm, 1152-pin FBGA)				KF40 (40 mm × 40 mm, 1517-pin FBGA)			NF40 (40 mm × 40 mm, 1517-pin FBGA)		
	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	
SX 270	48	336	24	_	_	_	_	_	_	
SX 320	48	336	24	_	_	_	_	_	_	
SX 480	48	348	36	_	_	_	_	_	_	
SX 570	48	348	36	96	600	36	48	540	48	
SX 660	48	348	36	96	600	36	48	540	48	

## **Related Information**

 ${\rm I/O}$  and High-Speed Differential  ${\rm I/O}$  Interfaces in Intel Arria 10 Devices chapter, Intel Arria 10 Device Handbook

Provides the number of 3 V and LVDS I/Os, and LVDS channels for each Intel Arria 10 device package.



## I/O Vertical Migration for Intel Arria 10 Devices

## Figure 4. Migration Capability Across Intel Arria 10 Product Lines

- The arrows indicate the migration paths. The devices included in each vertical migration path are shaded. Devices with fewer resources in the same path have lighter shades.
- To achieve the full I/O migration across product lines in the same migration path, restrict I/Os and transceivers usage to match the product line with the lowest I/O and transceiver counts.
- An LVDS I/O bank in the source device may be mapped to a 3 V I/O bank in the target device. To use
  memory interface clock frequency higher than 533 MHz, assign external memory interface pins only to
  banks that are LVDS I/O in both devices.
- There may be nominal 0.15 mm package height difference between some product lines in the same package type.
- Some migration paths are not shown in the Intel Quartus Prime software Pin Migration View.

Variant	Product						Package	e				
Varialit	Line	U19	F27	F29	F34	F35	KF40	NF40	RF40	NF45	SF45	UF45
	GX 160	<b>1</b>	<b>1</b>	<b>1</b>								
	GX 220	<b>+</b>										
	GX 270				1	<b>1</b>						
	GX 320		<b>V</b>									
Intel® Arria® 10 GX	GX 480			<b>V</b>								
	GX 570						<b>1</b>	1				
	GX 660					<b>V</b>	<b>\</b>					
	GX 900								1	1	<b></b>	1
	GX 1150				<b>V</b>			<b>+</b>	+	+		<b>+</b>
Intel Arria 10 GT	GT 900											
intel Afria 10 G1	GT 1150										<b>V</b>	
	SX 160	1	1	1								
	SX 220	+										
	SX 270				1	<b>†</b>						
Intel Arria 10 SX	SX 320		<b>V</b>									
	SX 480			<b>V</b>								
	SX 570						<b>†</b>	<b>†</b>				
	SX 660				<b>*</b>							

Note:

To verify the pin migration compatibility, use the **Pin Migration View** window in the Intel Quartus Prime software Pin Planner.

# **Adaptive Logic Module**

Intel Arria 10 devices use a 20 nm ALM as the basic building block of the logic fabric.

The ALM architecture is the same as the previous generation FPGAs, allowing for efficient implementation of logic functions and easy conversion of IP between the device generations.

The ALM, as shown in following figure, uses an 8-input fracturable look-up table (LUT) with four dedicated registers to help improve timing closure in register-rich designs and achieve an even higher design packing capability than the traditional two-register per LUT architecture.



Variant	Product Line	Product Line Variable- precision DSP Block		put and Output ons Operator	18 x 19 Multiplier	18 x 18 Multiplier Adder
		DSP BIOCK	18 x 19 Multiplier	27 x 27 Multiplier	Adder Sum Mode	Summed with 36 bit Input
	SX 320	984	1,968	984	984	984
	SX 480	1,368	2,736	1,368	1,368	1,368
	SX 570	1,523	3,046	1,523	1,523	1,523
	SX 660	1,687	3,374	1,687	1,687	1,687

Table 17. Resources for Floating-Point Arithmetic in Intel Arria 10 Devices

The table lists the variable-precision DSP resources by bit precision for each Intel Arria 10 device.

Variant	Product Line	Variable- precision DSP Block	Single Precision Floating-Point Multiplication Mode	Single-Precision Floating-Point Adder Mode	Single- Precision Floating-Point Multiply Accumulate Mode	Peak Giga Floating- Point Operations per Second (GFLOPs)
Intel Arria 10	GX 160	156	156	156	156	140
GX	GX 220	192	192	192	192	173
	GX 270	830	830	830	830	747
	GX 320	984	984	984	984	886
	GX 480	1,369	1,368	1,368	1,368	1,231
	GX 570	1,523	1,523	1,523	1,523	1,371
	GX 660	1,687	1,687	1,687	1,687	1,518
	GX 900	1,518	1,518	1,518	1,518	1,366
	GX 1150	1,518	1,518	1,518	1,518	1,366
Intel Arria 10	GT 900	1,518	1,518	1,518	1,518	1,366
GT	GT 1150	1,518	1,518	1,518	1,518	1,366
Intel Arria 10	SX 160	156	156	156	156	140
SX	SX 220	192	192	192	192	173
	SX 270	830	830	830	830	747
	SX 320	984	984	984	984	886
	SX 480	1,369	1,368	1,368	1,368	1,231
	SX 570	1,523	1,523	1,523	1,523	1,371
	SX 660	1,687	1,687	1,687	1,687	1,518

# **Embedded Memory Blocks**

The embedded memory blocks in the devices are flexible and designed to provide an optimal amount of small- and large-sized memory arrays to fit your design requirements.



### Table 20. Memory Standards Supported by the Hard Memory Controller

This table lists the overall capability of the hard memory controller. For specific details, refer to the External Memory Interface Spec Estimator and Intel Arria 10 Device Datasheet.

Memory Standard	Rate Support	Ping Pong PHY Support	Maximum Frequency (MHz)
DDR4 SDRAM	Quarter rate	Yes	1,067
		_	1,200
DDR3 SDRAM	Half rate	Yes	533
		_	667
	Quarter rate	Yes	1,067
		_	1,067
DDR3L SDRAM	Half rate	Yes	533
		_	667
	Quarter rate	Yes	933
		_	933
LPDDR3 SDRAM	Half rate	_	533
	Quarter rate	_	800

## Table 21. Memory Standards Supported by the Soft Memory Controller

Memory Standard	Rate Support	Maximum Frequency (MHz)	
RLDRAM 3 (11)	Quarter rate	1,200	
QDR IV SRAM <sup>(11)</sup>	Quarter rate	1,067	
QDR II SRAM	Full rate	333	
	Half rate	633	
QDR II+ SRAM	Full rate	333	
	Half rate	633	
QDR II+ Xtreme SRAM	Full rate	333	
	Half rate	633	

## Table 22. Memory Standards Supported by the HPS Hard Memory Controller

The hard processor system (HPS) is available in Intel Arria 10 SoC devices only.

Memory Standard	Rate Support	Maximum Frequency (MHz)
DDR4 SDRAM	Half rate	1,200
DDR3 SDRAM	Half rate	1,067
DDR3L SDRAM	Half rate	933

<sup>(11)</sup> Intel Arria 10 devices support this external memory interface using hard PHY with soft memory controller.

## A10-OVERVIEW | 2018.04.09



The scalable hard IP supports multiple independent 10GbE ports while using a single PLL for all the 10GBASE-R PCS instantiations, which saves on core logic resources and clock networks:

- Simplifies multiport 10GbE systems compared to XAUI interfaces that require an external XAUI-to-10G PHY.
- Incorporates Electronic Dispersion Compensation (EDC), which enables direct connection to standard 10 Gbps XFP and SFP+ pluggable optical modules.
- Supports backplane Ethernet applications and includes a hard 10GBASE-KR Forward Error Correction (FEC) circuit that you can use for 10 Gbps and 40 Gbps applications.

The 10 Gbps Ethernet PCS hard IP and 10GBASE-KR FEC are present in every transceiver channel.

#### **Related Information**

PCS Features on page 30

## **Low Power Serial Transceivers**

Intel Arria 10 FPGAs and SoCs include lowest power transceivers that deliver high bandwidth, throughput and low latency.

Intel Arria 10 devices deliver the industry's lowest power consumption per transceiver channel:

- 12.5 Gbps transceivers at as low as 242 mW
- 10 Gbps transceivers at as low as 168 mW
- 6 Gbps transceivers at as low as 117 mW

Intel Arria 10 transceivers support various data rates according to application:

- Chip-to-chip and chip-to-module applications—from 1 Gbps up to 25.8 Gbps
- Long reach and backplane applications—from 1 Gbps up to 12.5 with advanced adaptive equalization
- Critical power sensitive applications—from 1 Gbps up to 11.3 Gbps using lower power modes

The combination of 20 nm process technology and architectural advances provide the following benefits:

- Significant reduction in die area and power consumption
- Increase of up to two times in transceiver I/O density compared to previous generation devices while maintaining optimal signal integrity
- Up to 72 total transceiver channels—you can configure up to 6 of these channels to run as fast as 25.8 Gbps
- All channels feature continuous data rate support up to the maximum rated speed



Figure 7. Device Chip Overview for Intel Arria 10 GX and GT Devices



Figure 8. Device Chip Overview for Intel Arria 10 SX Devices



## **PMA Features**

Intel Arria 10 transceivers provide exceptional signal integrity at data rates up to 25.8 Gbps. Clocking options include ultra-low jitter ATX PLLs (LC tank based), clock multiplier unit (CMU) PLLs, and fractional PLLs.



Figure 9. HPS Block Diagram

This figure shows a block diagram of the HPS with the dual ARM Cortex-A9 MPCore processor.



# **Key Advantages of 20-nm HPS**

The 20-nm HPS strikes a balance between enabling maximum software compatibility with 28-nm SoCs while still improving upon the 28-nm HPS architecture. These improvements address the requirements of the next generation target markets such as wireless and wireline communications, compute and storage equipment, broadcast and military in terms of performance, memory bandwidth, connectivity via backplane and security.



#### Features of the HPS

The HPS has the following features:

- 1.2-GHz, dual-core ARM Cortex-A9 MPCore processor with up to 1.5-GHz via overdrive
  - ARMv7-A architecture that runs 32-bit ARM instructions, 16-bit and 32-bit
     Thumb instructions, and 8-bit Java byte codes in Jazelle style
  - Superscalar, variable length, out-of-order pipeline with dynamic branch prediction
  - Instruction Efficiency 2.5 MIPS/MHz, which provides total performance of 7500 MIPS at 1.5 GHz
- Each processor core includes:
  - 32 KB of L1 instruction cache, 32 KB of L1 data cache
  - Single- and double-precision floating-point unit and NEON media engine
  - CoreSight debug and trace technology
  - Snoop Control Unit (SCU) and Acceleration Coherency Port (ACP)
- 512 KB of shared L2 cache
- 256 KB of scratch RAM
- Hard memory controller with support for DDR3, DDR4 and optional error correction code (ECC) support
- Multiport Front End (MPFE) Scheduler interface to the hard memory controller
- 8-channel direct memory access (DMA) controller
- QSPI flash controller with SIO, DIO, QIO SPI Flash support
- NAND flash controller (ONFI 1.0 or later) with DMA and ECC support, updated to support 8 and 16-bit Flash devices and new command DMA to offload CPU for fast power down recovery
- Updated SD/SDIO/MMC controller to eMMC 4.5 with DMA with CE-ATA digital command support
- 3 10/100/1000 Ethernet media access control (MAC) with DMA
- 2 USB On-the-Go (OTG) controllers with DMA
- 5 I<sup>2</sup>C controllers (3 can be used by EMAC for MIO to external PHY)
- 2 UART 16550 Compatible controllers
- 4 serial peripheral interfaces (SPI) (2 Master, 2 Slaves)
- 62 programmable general-purpose I/Os, which includes 48 direct share I/Os that allows the HPS peripherals to connect directly to the FPGA I/Os
- 7 general-purpose timers
- 4 watchdog timers
- Anti-tamper, Secure Boot, Encryption (AES) and Authentication (SHA)



Scheme	Data Width	Max Clock Rate (MHz)	Max Data Rate (Mbps)	Decompression	Design Security <sup>(1</sup> 4)	Partial Reconfiguration (15)	Remote System Update
Fast passive	8 bits	100	3200	Yes	Yes	Yes <sup>(17)</sup>	PFL IP
parallel (FPP) through CPLD or	16 bits			Yes	Yes		core
external microcontroller	32 bits			Yes	Yes		
Configuration via	16 bits	100	3200	Yes	Yes	Yes <sup>(17)</sup>	_
HPS	32 bits			Yes	Yes		
Configuration via Protocol [CvP (PCIe*)]	x1, x2, x4, x8 lanes	_	8000	Yes	Yes	Yes <sup>(16)</sup>	_

You can configure Intel Arria 10 devices through PCIe using Configuration via Protocol (CvP). The Intel Arria 10 CvP implementation conforms to the PCIe 100 ms power-up-to-active time requirement.

## **SEU Error Detection and Correction**

Intel Arria 10 devices offer robust and easy-to-use single-event upset (SEU) error detection and correction circuitry.

The detection and correction circuitry includes protection for Configuration RAM (CRAM) programming bits and user memories. The CRAM is protected by a continuously running CRC error detection circuit with integrated ECC that automatically corrects one or two errors and detects higher order multi-bit errors. When more than two errors occur, correction is available through reloading of the core programming file, providing a complete design refresh while the FPGA continues to operate.

The physical layout of the Intel Arria 10 CRAM array is optimized to make the majority of multi-bit upsets appear as independent single-bit or double-bit errors which are automatically corrected by the integrated CRAM ECC circuitry. In addition to the CRAM protection, the M20K memory blocks also include integrated ECC circuitry and are layout-optimized for error detection and correction. The MLAB does not have ECC.

## **Power Management**

Intel Arria 10 devices leverage the advanced 20 nm process technology, a low 0.9 V core power supply, an enhanced core architecture, and several optional power reduction techniques to reduce total power consumption by as much as 40% compared to Arria V devices and as much as 60% compared to Stratix V devices.

<sup>(13)</sup> Enabling either compression or design security features affects the maximum data rate. Refer to the Intel Arria 10 Device Datasheet for more information.

<sup>(14)</sup> Encryption and compression cannot be used simultaneously.

<sup>(15)</sup> Partial reconfiguration is an advanced feature of the device family. If you are interested in using partial reconfiguration, contact Intel for support.

<sup>(17)</sup> Supported at a maximum clock rate of 100 MHz.



The optional power reduction techniques in Intel Arria 10 devices include:

- SmartVID—a code is programmed into each device during manufacturing that allows a smart regulator to operate the device at lower core V<sub>CC</sub> while maintaining performance
- **Programmable Power Technology**—non-critical timing paths are identified by the Intel Quartus Prime software and the logic in these paths is biased for low power instead of high performance
- **Low Static Power Options**—devices are available with either standard static power or low static power while maintaining performance

Furthermore, Intel Arria 10 devices feature Intel's industry-leading low power transceivers and include a number of hard IP blocks that not only reduce logic resources but also deliver substantial power savings compared to soft implementations. In general, hard IP blocks consume up to 90% less power than the equivalent soft logic implementations.

## **Incremental Compilation**

The Intel Quartus Prime software incremental compilation feature reduces compilation time and helps preserve performance to ease timing closure. The incremental compilation feature enables the partial reconfiguration flow for Intel Arria 10 devices.

Incremental compilation supports top-down, bottom-up, and team-based design flows. This feature facilitates modular, hierarchical, and team-based design flows where different designers compile their respective design sections in parallel. Furthermore, different designers or IP providers can develop and optimize different blocks of the design independently. These blocks can then be imported into the top level project.

# **Document Revision History for Intel Arria 10 Device Overview**

Document Version	Changes
2018.04.09	Updated the lowest $V_{CC}$ from 0.83 V to 0.82 V in the topic listing a summary of the device features.

Date	Version	Changes
January 2018	2018.01.17	Updated the maximum data rate for HPS (Intel Arria 10 SX devices external memory interface DDR3 controller from 2,166 Mbps to 2,133 Mbps.
		Updated maximum frequency supported for half rate QDRII and QDRII     + SRAM to 633 MHz in Memory Standards Supported by the Soft     Memory Controller table.
		Updated transceiver backplane capability to 12.5 Gbps.
		Removed transceiver speed grade 5 in Sample Ordering Core and Available Options for Intel Arria 10 GX Devices figure.
	·	continued

## A10-OVERVIEW | 2018.04.09



July 2017 2017.  July 2017 2017.  May 2017 2017.  March 2017 2017.  October 2016 2016.  May 2016 2016.	sion	Changes
July 2017 2017.  July 2017 2017.  May 2017 2017.  March 2017 2017.  October 2016 2016.  May 2016 2016.		<ul> <li>Removed package code 40, low static power, SmartVID, industrial, and military operating temperature support from Sample Ordering Core and Available Options for Intel Arria 10 GT Devices figure.</li> <li>Updated short reach transceiver rate for Intel Arria 10 GT devices to 25.8 Gbps.</li> <li>Removed On-Die Instrumentation — EyeQ and Jitter Margin Tool support from PMA Features of the Transceivers in Intel Arria 10 Devices table.</li> </ul>
July 2017 2017.  May 2017 2017.  March 2017 2017.  October 2016 2016.  May 2016 2016.	.09.20	Updated the maximum speed of the DDR4 external memory interface from 1,333 MHz/2,666 Mbps to 1,200 MHz/2,400 Mbps.
May 2017 2017.  March 2017 2017.  October 2016 2016.  May 2016 2016.	.07.13	Corrected the automotive temperature range in the figure showing the available options for the Intel Arria 10 GX devices from "-40°C to 100°C" to "-40°C to 125°C".
March 2017 2017.  October 2016 2016.  May 2016 2016.	07.06	Added automotive temperature option to Intel Arria 10 GX device family.
October 2016 2016.  May 2016 2016.	.05.08	<ul> <li>Corrected protocol names with "1588" to "IEEE 1588v2".</li> <li>Updated the vertical migration table to remove vertical migration between Intel Arria 10 GX and Intel Arria 10 SX device variants.</li> <li>Removed all "Preliminary" marks.</li> </ul>
May 2016 2016.	.03.15	Removed the topic about migration from Intel Arria 10 to Intel Stratix 10 devices. Rebranded as Intel.
,	.10.31	<ul> <li>Removed package F36 from Intel Arria 10 GX devices.</li> <li>Updated Intel Arria 10 GT sample ordering code and maximum GX transceiver count. Intel Arria 10 GT devices are available only in the SF45 package option with a maximum of 72 transceivers.</li> </ul>
February 2016 2016.	05.02	Updated the FPGA Configuration and HPS Booting topic. Remove V <sub>CC</sub> PowerManager from the Summary of Features, Power Management and Arria 10 Device Variants and packages topics. This feature is no longer supported in Arria 10 devices. Removed LPDDR3 from the Memory Standards Supported by the HPS Hard Memory Controller table in the Memory Standards Supported by Intel Arria 10 Devices topic. This standard is only supported by the FPGA. Removed transceiver speed grade 5 from the Device Variants and Packages topic for Arria 10 GX and SX devices.
	02.11	<ul> <li>Changed the maximum Arria 10 GT datarate to 25.8 Gbps and the minimum datarate to 1 Gbps globally.</li> <li>Revised the state for Core clock networks in the Summary of Features topic.</li> <li>Changed the transceiver parameters in the "Summary of Features for Arria 10 Devices" table.</li> <li>Changed the transceiver parameters in the "Maximum Resource Counts for Arria 10 GT Devices" table.</li> <li>Changed the package availability for GT devices in the "Package Plan for Arria 10 GT Devices" table.</li> <li>Changed the package configurations for GT devices in the "Migration Capability Across Arria 10 Product Lines" figure.</li> <li>Changed transceiver parameters in the "Low Power Serial Transceivers" section.</li> <li>Changed the transceiver descriptions in the "Device Variants for the Arria 10 Device Family" table.</li> <li>Changed the "Sample Ordering Code and Available Options for Arria 10 GT Devices" figure.</li> <li>Changed the datarates for GT devices in the "PMA Features" section.</li> <li>Changed the datarates for GT devices in the "PCS Features" section.</li> </ul>



Date	Version	Changes
December 2015	2015.12.14	Updated the number of M20K memory blocks for Arria 10 GX 660 from 2133 to 2131 and corrected the total RAM bit from 48,448 Kb to 48,408 Kb.
		Corrected the number of DSP blocks for Arria 10 GX 660 from 1688 to 1687 in the table listing floating-point arithmetic resources.
November 2015	2015.11.02	• Updated the maximum resources for Arria 10 GX 220, GX 320, GX 480, GX 660, SX 220, SX 320, SX 480, and SX 660.
		Updated resource count for Arria 10 GX 320, GX 480, GX 660, SX 320, SX 480, a SX 660 devices in <b>Number of Multipliers in Intel Arria 10 Devices</b> table.
		<ul> <li>Updated the available options for Arria 10 GX, GT, and SX.</li> <li>Changed instances of <i>Quartus II</i> to <i>Quartus Prime</i>.</li> </ul>
June 2015	2015.06.15	Corrected label for Intel Arria 10 GT product lines in the vertical migration figure.
May 2015	2015.05.15	Corrected the DDR3 half rate and quarter rate maximum frequencies in the table that lists the memory standards supported by the Intel Arria 10 hard memory controller.
May 2015	2015.05.04	Added support for 13.5G JESD204b in the Summary of Features table.  Added support for 13.5G JESD204b in the Summary of Features table.
		Added a link to Arria 10 GT Channel Usage in the Arria 10 GT Package Plan topic.
		Added a note to the table, Maximum Resource Counts for Arria 10 GT devices.
		Updated the power requirements of the transceivers in the Low Power Serial Transceivers topic.
January 2015	2015.01.23	Added floating point arithmetic features in the Summary of Features table.
		Updated the total embedded memory from 38.38 megabits (Mb) to 65.6 Mb.
		Updated the table that lists the memory standards supported by Intel Arria 10 devices.
		<ul> <li>Removed support for DDR3U, LPDDR3 SDRAM, RLDRAM 2, and DDR2.</li> <li>Moved RLDRAM 3 support from hard memory controller to soft memory controller. RLDRAM 3 support uses hard PHY with soft memory controller.</li> </ul>
		Added soft memory controller support for QDR IV.
		Updated the maximum resource count table to include the number of hard memory controllers available in each device variant.
		Updated the transceiver PCS data rate from 12.5 Gbps to 12 Gbps.
		Updated the max clock rate of PS, FPP x8, FPP x16, and Configuration via HPS from 125 MHz to 100 MHz.
		Added a feature for fractional synthesis PLLs: PLL cascading.
		Updated the HPS programmable general-purpose I/Os from 54 to 62.
September 2014	2014.09.30	Corrected the 3 V I/O and LVDS I/O counts for F35 and F36 packages of Arria 10 GX.
		Corrected the 3 V I/O, LVDS I/O, and transceiver counts for the NF40 package of the Arria GX 570 and 660.
		Removed 3 V I/O, LVDS I/O, and transceiver counts for the NF40 package of the Arria GX 900 and 1150. The NF40 package is not available for Arria 10 GX 900 and 1150.
		continued